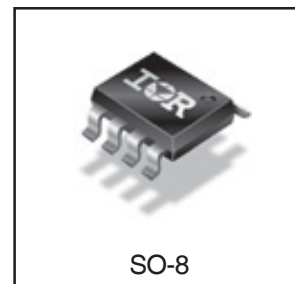
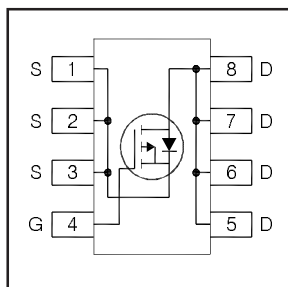


# IRF9392PbF

HEXFET® Power MOSFET

$V_{DS}$	<b>-30</b>	<b>V</b>
$V_{GS\ max}$	<b>±25</b>	<b>V</b>
$R_{DS(on)\ max}$ (@ $V_{GS} = -10V$ )	<b>17.5</b>	<b>mΩ</b>
$I_D$ (@ $T_A = 25^\circ C$ )	<b>-9.8</b>	<b>A</b>



## Applications

- Adaptor Input Switch for Notebook PC

## Features and Benefits

### Features

25V $V_{GS\ max}$
Industry-Standard SO8 Package
RoHS Compliant Containing no Lead, no Bromide and no Halogen

### Resulting Benefits

Direct Drive at High $V_{GS}$
Multi-Vendor Compatibility
Environmentally Friendlier

Orderable part number	Package Type	Standard Pack		Note
		Form	Quantity	
IRF9392PbF	SO8	Tube/Bulk	95	
IRF9392TRPbF	SO8	Tape and Reel	4000	

## Absolute Maximum Ratings

	Parameter	Max.	Units
$V_{DS}$	Drain-to-Source Voltage	-30	V
$V_{GS}$	Gate-to-Source Voltage	±25	
$I_D @ T_A = 25^\circ C$	Continuous Drain Current, $V_{GS} @ -10V$	-9.8	A
$I_D @ T_A = 70^\circ C$	Continuous Drain Current, $V_{GS} @ -10V$	-7.8	
$I_{DM}$	Pulsed Drain Current ①	-80	
$P_D @ T_A = 25^\circ C$	Power Dissipation ②	2.5	W
$P_D @ T_A = 70^\circ C$	Power Dissipation ②	1.6	
	Linear Derating Factor	0.02	W/°C
$T_J$ $T_{STG}$	Operating Junction and Storage Temperature Range	-55 to + 150	°C

Notes ① through ⑥ are on page 2

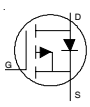
## Static @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$BV_{DSS}$	Drain-to-Source Breakdown Voltage	-30	—	—	V	$V_{GS} = 0V, I_D = -250\mu A$
$\Delta BV_{DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	0.021	—	V/ $^\circ\text{C}$	Reference to $25^\circ\text{C}, I_D = -1\text{mA}$
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	—	13.6	17.5	m $\Omega$	$V_{GS} = -10V, I_D = -9.8A$ ③
		—	12.1	—		$V_{GS} = -20V, I_D = -7.8A$ ③
$V_{GS(th)}$	Gate Threshold Voltage	-1.3	-1.9	-2.4	V	$V_{DS} = V_{GS}, I_D = -25\mu A$
$\Delta V_{GS(th)}$	Gate Threshold Voltage Coefficient	—	-5.7	—	mV/ $^\circ\text{C}$	
$I_{DSS}$	Drain-to-Source Leakage Current	—	—	-1.0	$\mu A$	$V_{DS} = -24V, V_{GS} = 0V$
		—	—	-150		$V_{DS} = -24V, V_{GS} = 0V, T_J = 125^\circ\text{C}$
$I_{GSS}$	Gate-to-Source Forward Leakage	—	—	-10	$\mu A$	$V_{GS} = -25V$
	Gate-to-Source Reverse Leakage	—	—	10		$V_{GS} = 25V$
$g_{fs}$	Forward Transconductance	36	—	—	S	$V_{DS} = -10V, I_D = -7.8A$
$Q_g$	Total Gate Charge ⑥	—	14	—	nC	$V_{DS} = -15V, V_{GS} = -4.5V, I_D = -7.8A$
$Q_{gs}$	Gate-to-Source Charge ⑥	—	4.1	—	nC	$V_{GS} = -10V$
$Q_{gd}$	Gate-to-Drain Charge ⑥	—	6.6	—		$V_{DS} = -15V$ $I_D = -7.8A$
$R_G$	Gate Resistance ⑥	—	18	—	$\Omega$	
$t_{d(on)}$	Turn-On Delay Time	—	15	—	ns	$V_{DD} = -15V, V_{GS} = -4.5V$ ③ $I_D = -1.0A$ $R_G = 6.8\Omega$ See Figs. 19a & 19b
$t_r$	Rise Time	—	47	—		
$t_{d(off)}$	Turn-Off Delay Time	—	73	—		
$t_f$	Fall Time	—	58	—		
$C_{iss}$	Input Capacitance	—	1270	—	pF	$V_{GS} = 0V$
$C_{oss}$	Output Capacitance	—	250	—		$V_{DS} = -25V$
$C_{rss}$	Reverse Transfer Capacitance	—	180	—		$f = 1.0\text{KHz}$

## Avalanche Characteristics

	Parameter	Typ.	Max.	Units
$E_{AS}$	Single Pulse Avalanche Energy ②	—	102	mJ
$I_{AR}$	Avalanche Current ①	—	-7.8	A

## Diode Characteristics

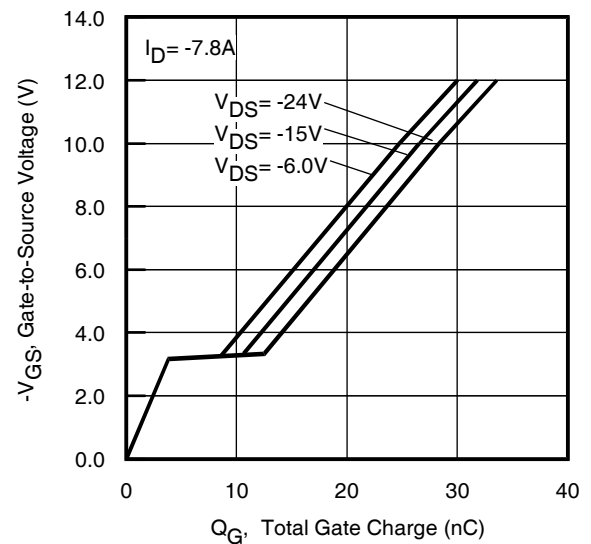
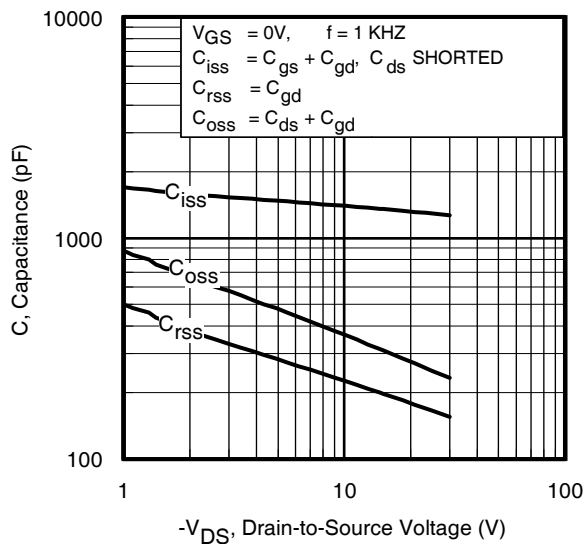
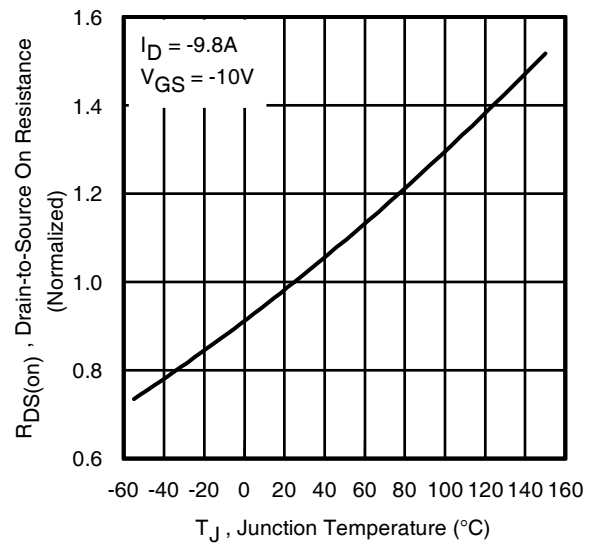
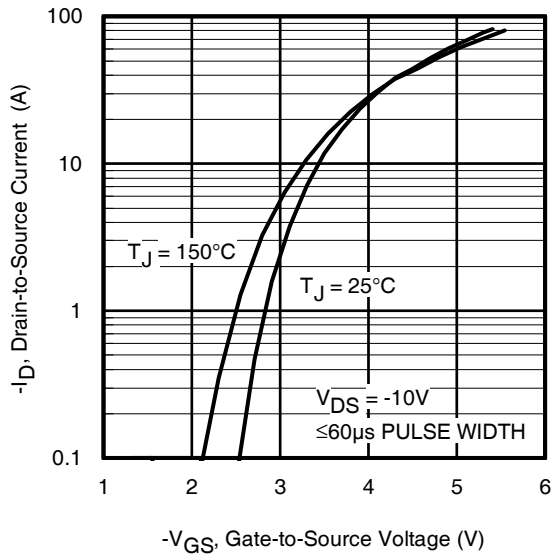
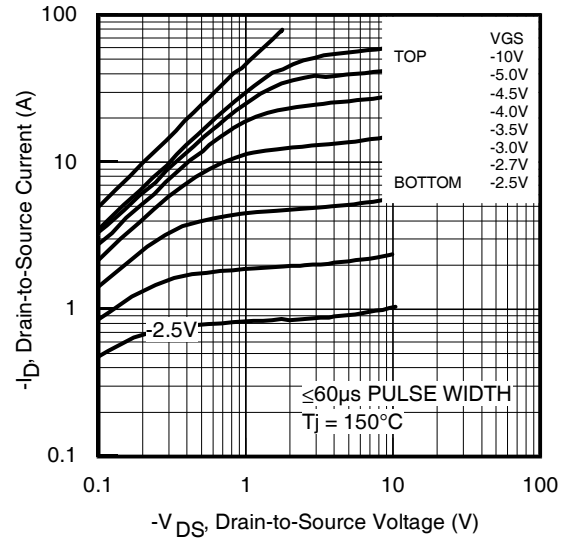
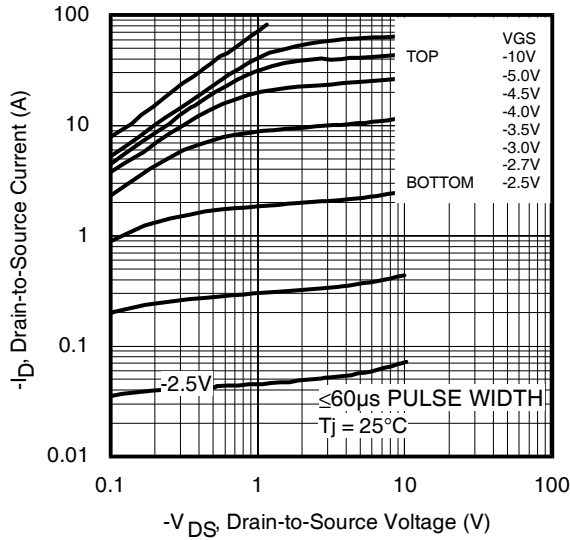
	Parameter	Min.	Typ.	Max.	Units	Conditions
$I_S$	Continuous Source Current (Body Diode)	—	—	-2.5	A	MOSFET symbol showing the integral reverse p-n junction diode. 
$I_{SM}$	Pulsed Source Current (Body Diode) ①	—	—	-80		
$V_{SD}$	Diode Forward Voltage	—	—	-1.2	V	$T_J = 25^\circ\text{C}, I_S = -2.5A, V_{GS} = 0V$ ③
$t_{rr}$	Reverse Recovery Time	—	36	54	ns	$T_J = 25^\circ\text{C}, I_F = -2.5A, V_{DD} = -24V$
$Q_{rr}$	Reverse Recovery Charge	—	20	30	nC	$di/dt = 100/\mu s$ ③

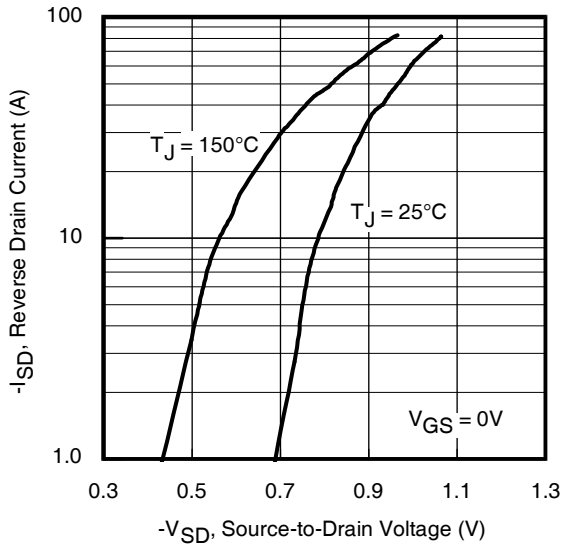
## Thermal Resistance

	Parameter	Typ.	Max.	Units
$R_{\theta JL}$	Junction-to-Drain Lead ⑤	—	20	$^\circ\text{C}/W$
$R_{\theta JA}$	Junction-to-Ambient ④	—	50	

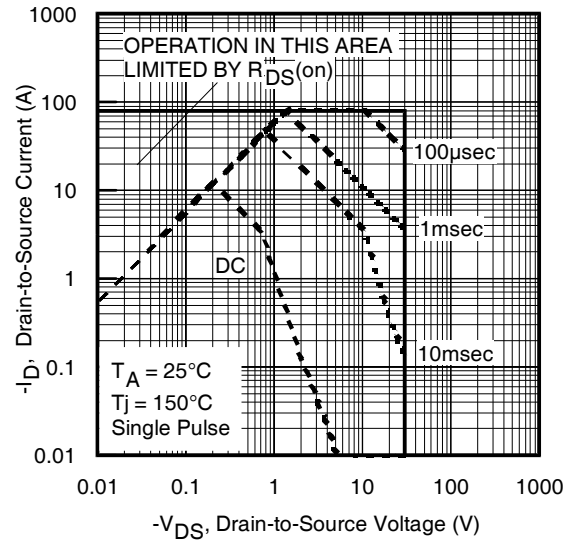
### Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Starting  $T_J = 25^\circ\text{C}, L = 3.3\text{mH}, R_G = 25\Omega, I_{AS} = -7.8A$ .
- ③ Pulse width  $\leq 400\mu s$ ; duty cycle  $\leq 2\%$ .
- ④ When mounted on 1 inch square copper board.
- ⑤  $R_\theta$  is measured at  $T_J$  of approximately  $90^\circ\text{C}$ .
- ⑥ For DESIGN AID ONLY, not subject to production testing.

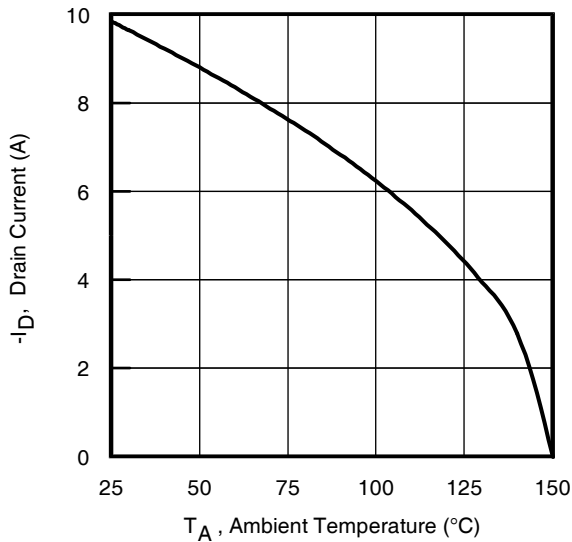




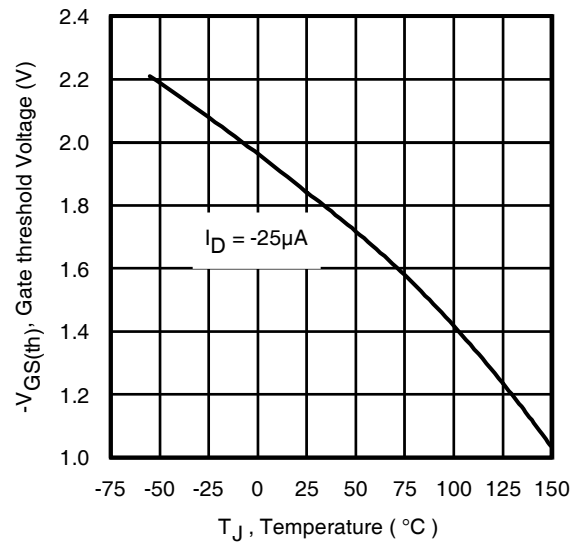
**Fig 7.** Typical Source-Drain Diode Forward Voltage



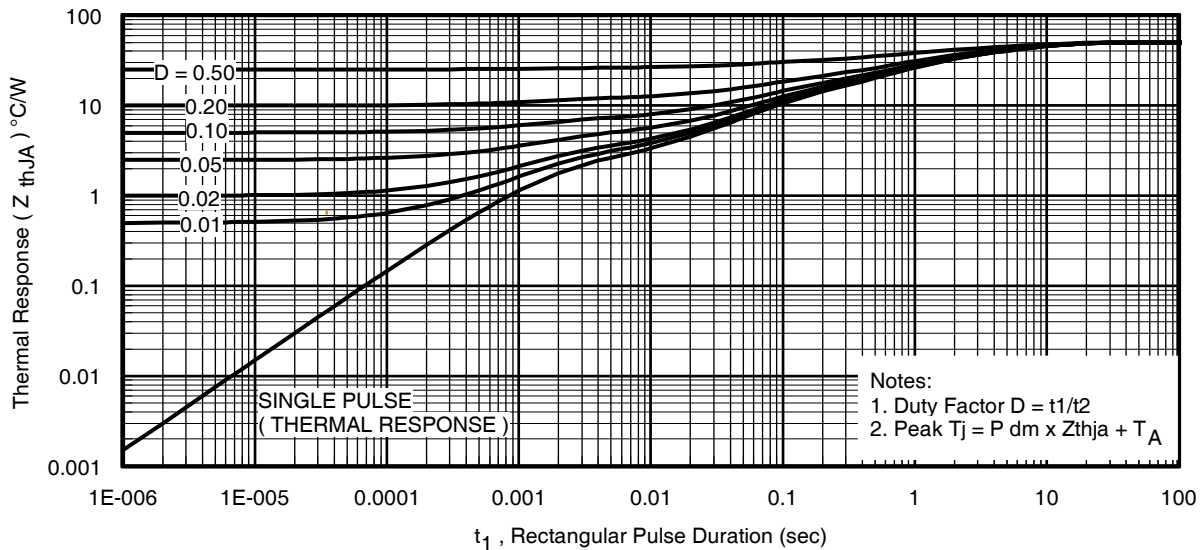
**Fig 8.** Maximum Safe Operating Area



**Fig 9.** Maximum Drain Current vs. Ambient Temperature



**Fig 10.** Threshold Voltage vs. Temperature



**Fig 11.** Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

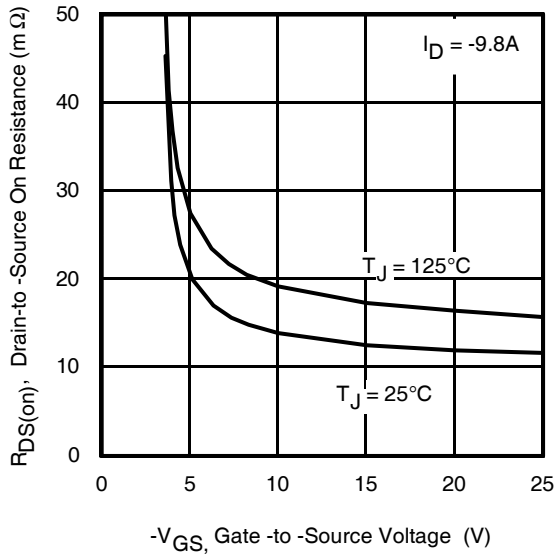


Fig 12. On-Resistance vs. Gate Voltage

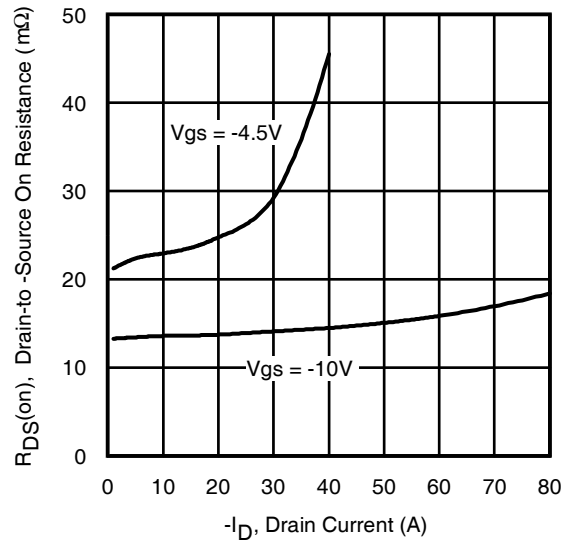


Fig 13. Typical On-Resistance vs. Drain Current

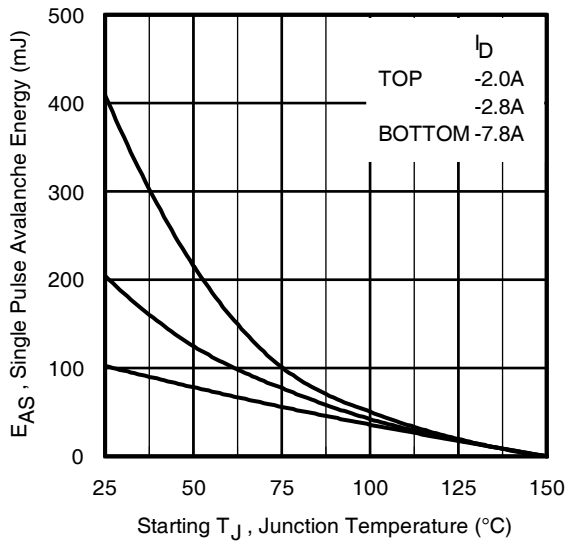


Fig 14. Maximum Avalanche Energy vs. Drain Current

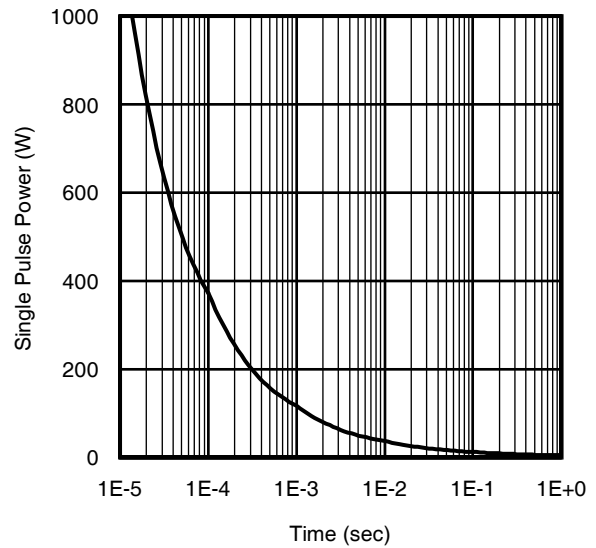
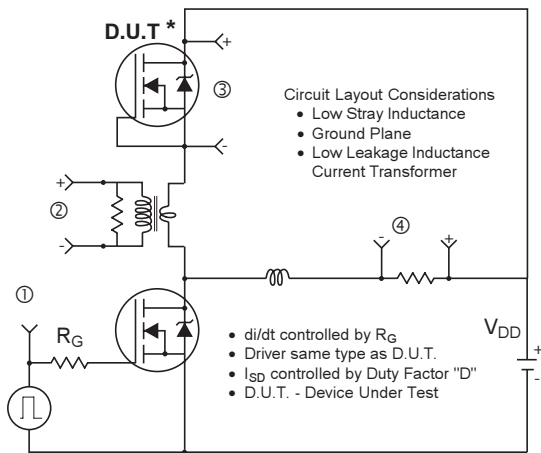
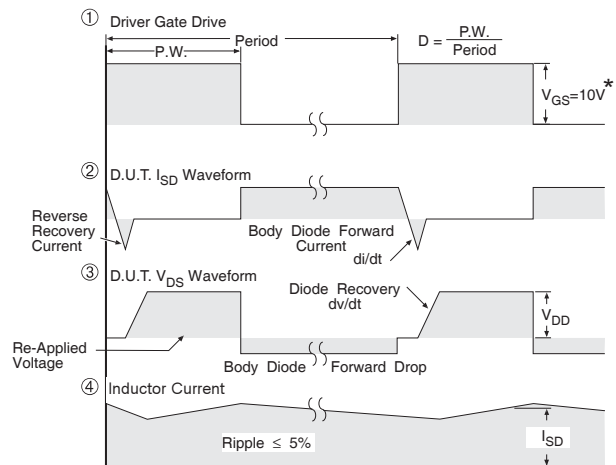


Fig 15. Typical Power vs. Time

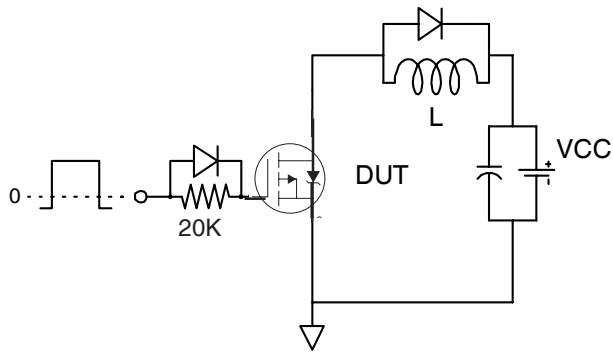


\* Reverse Polarity of D.U.T for P-Channel



\* V<sub>GS</sub> = 5V for Logic Level Devices

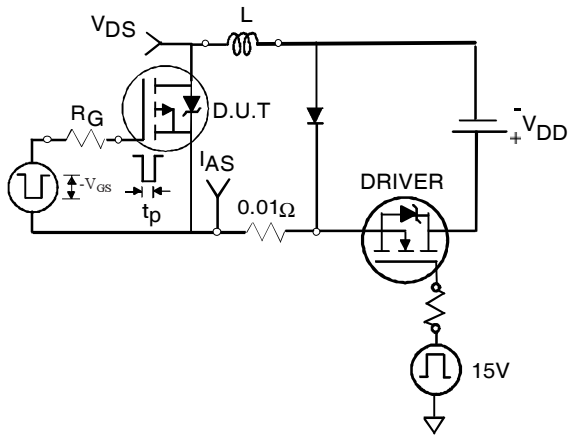
Fig 16. Diode Reverse Recovery Test Circuit for P-Channel HEXFET® Power MOSFETs



**Fig 17a.** Gate Charge Test Circuit



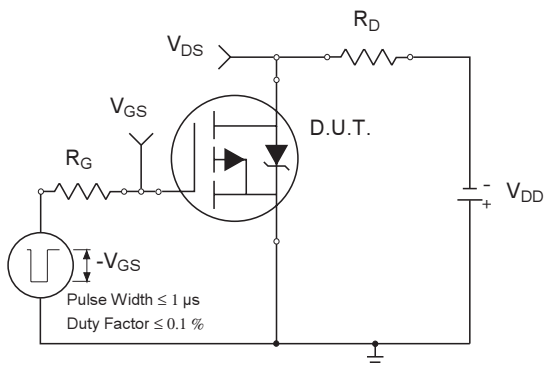
**Fig 17b.** Gate Charge Waveform



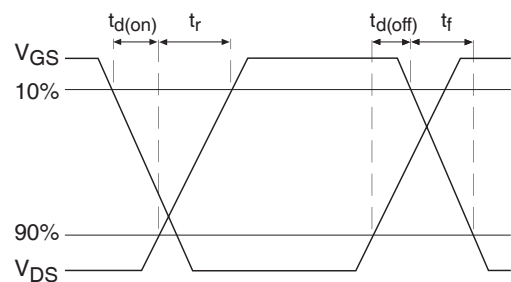
**Fig 18a.** Unclamped Inductive Test Circuit



**Fig 18b.** Unclamped Inductive Waveforms



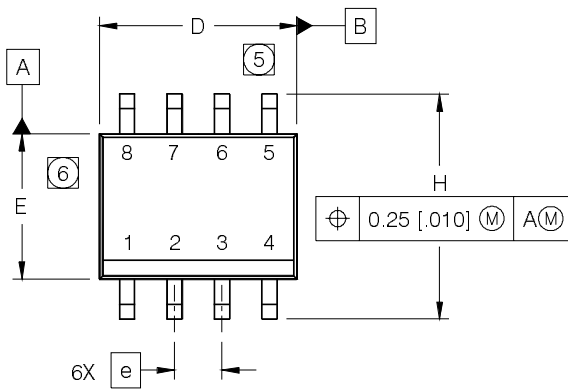
**Fig 19a.** Switching Time Test Circuit



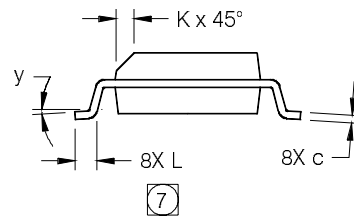
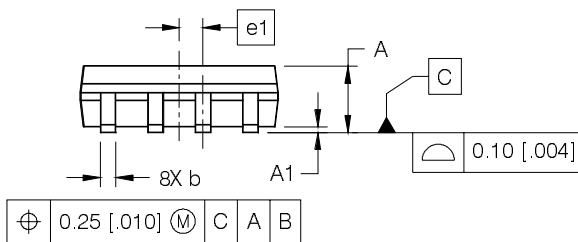
**Fig 19b.** Switching Time Waveforms

## SO-8 Package Outline (MOSFET & Fetky)

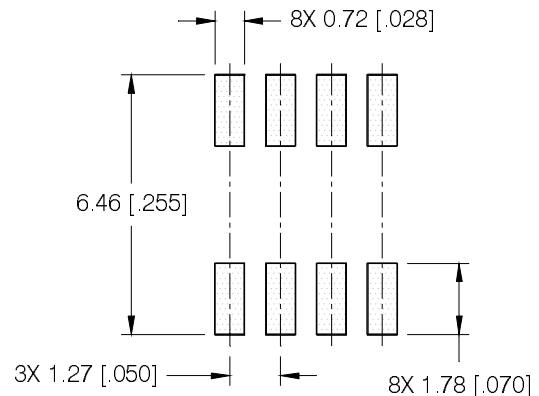
Dimensions are shown in millimeters (inches)



DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.0532	.0688	1.35	1.75
A1	.0040	.0098	0.10	0.25
b	.013	.020	0.33	0.51
c	.0075	.0098	0.19	0.25
D	.189	.1968	4.80	5.00
E	.1497	.1574	3.80	4.00
e	.050 BASIC		1.27 BASIC	
e 1	.025 BASIC		0.635 BASIC	
H	.2284	.2440	5.80	6.20
K	.0099	.0196	0.25	0.50
L	.016	.050	0.40	1.27
y	0°	8°	0°	8°



### FOOTPRINT

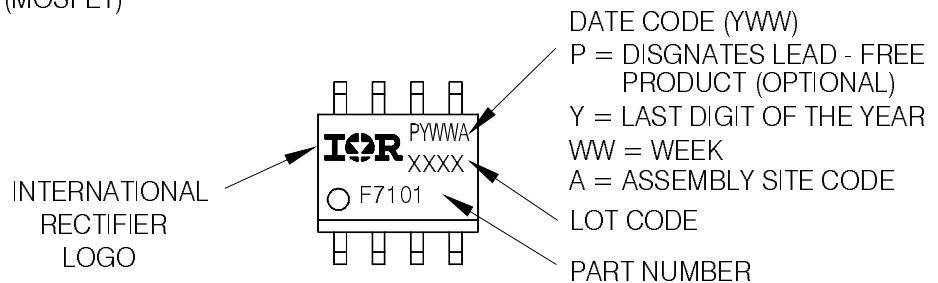


### NOTES:

1. DIMENSIONING & TOLERANCING PER ASME Y14.5M-1994.
2. CONTROLLING DIMENSION: MILLIMETER
3. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
4. OUTLINE CONFORMS TO JEDEC OUTLINE MS-012AA.
- ⑤ DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS. MOLD PROTRUSIONS NOT TO EXCEED 0.15 [.006].
- ⑥ DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS. MOLD PROTRUSIONS NOT TO EXCEED 0.25 [.010].
- ⑦ DIMENSION IS THE LENGTH OF LEAD FOR SOLDERING TO A SUBSTRATE.

## SO-8 Part Marking Information

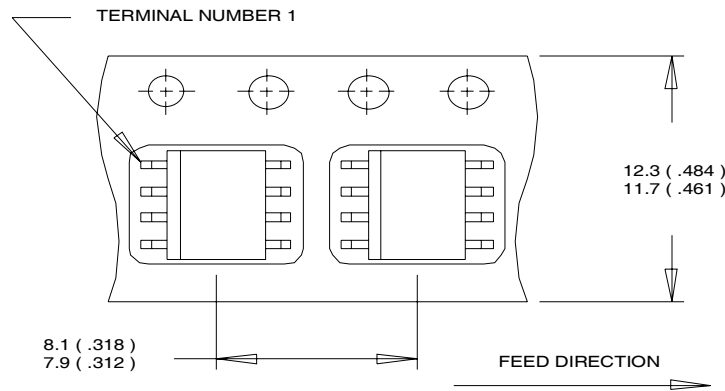
EXAMPLE: THIS IS AN IRF7101 (MOSFET)



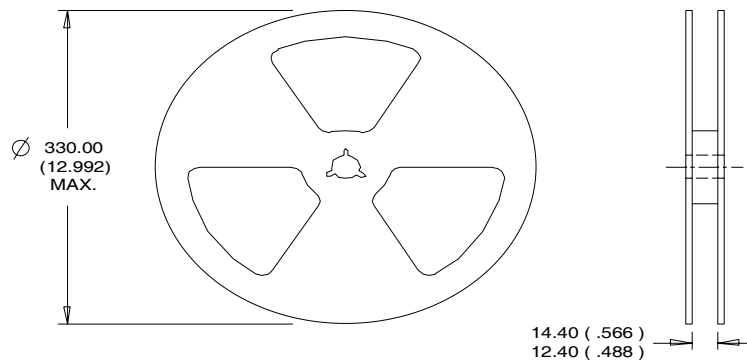
Note: For the most current drawing please refer to IR website at <http://www.irf.com/package/>

# IRF9392PbF

SO-8 Tape and Reel (Dimensions are shown in millimeters (inches))



- NOTES:
1. CONTROLLING DIMENSION : MILLIMETER.
  2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS(INCHES).
  3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



- NOTES :
1. CONTROLLING DIMENSION : MILLIMETER.
  2. OUTLINE CONFORMS TO EIA-481 & EIA-541.

## Qualification Information<sup>†</sup>

Qualification level	Consumer <sup>††</sup> (per JEDEC JESD47F <sup>†††</sup> guidelines)	
Moisture Sensitivity Level	SO-8	MSL1 (per JEDEC J-STD-020D <sup>†††</sup> )
RoHS Compliant	Yes	

† Qualification standards can be found at International Rectifier's web site  
<http://www.irf.com/product-info/reliability>

†† Higher qualification ratings may be available should the user have such requirements.  
Please contact your International Rectifier sales representative for further information:  
<http://www.irf.com/whoto-call/salesrep/>

††† Applicable version of JEDEC standard at the time of product release.

Data and specifications subject to change without notice.